



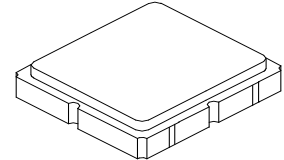
AEC-Q200
 This component was always
 RoHS compliant from the first
 date of manufacture.

- Surface Mount 3.0 x 3.0 mm Package
- Complies with Directive 2002/95/EC (RoHS)



SF2412E

**925 MHz
 SAW Filter**



SM3030-6

Absolute Maximum Ratings

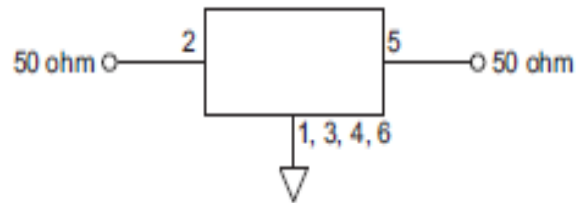
Rating	Value	Units
Input Power Level	18	dBm
DC Voltage on any Non-ground Terminal	5	V
Operating Temperature Range	-40 to +85	°C
Storage Temperature Range in Tape and Reel	-40 to +85	°C

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Center Frequency	f_c			925		MHz
Insertion Loss 922 to 928 MHz	IL			2.6	3.8	dB
Amplitude Ripple 922 to 928 MHz				0.7	2.0	
Insertion Loss, (920 to 930 MHz)	IL			3.2	4.6	
Amplitude Ripple, (920 to 930 MHz)				0.7	2.0	
Attenuation, Referenced from 0 dB:						dB
775 to 835 MHz			40	46		
835 to 895 MHz			36	45		
945 to 960 MHz			24	34		
970 to 992 MHz			36	46		
992 to 1075 MHz			38	44		
Source Impedance Z_S				50		Ω
Load Impedance Z_L				50		
Case Style	SM3030-6 3.0 x 3.0 mm Nominal Footprint					
Lid Symbolization (Y=year, WW=week, S=shift) dot=pin 1 indicator	7V, YWWS					

Electrical Connections

Connection	Terminals
Input	2
Output	5
Case Ground	All others



CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

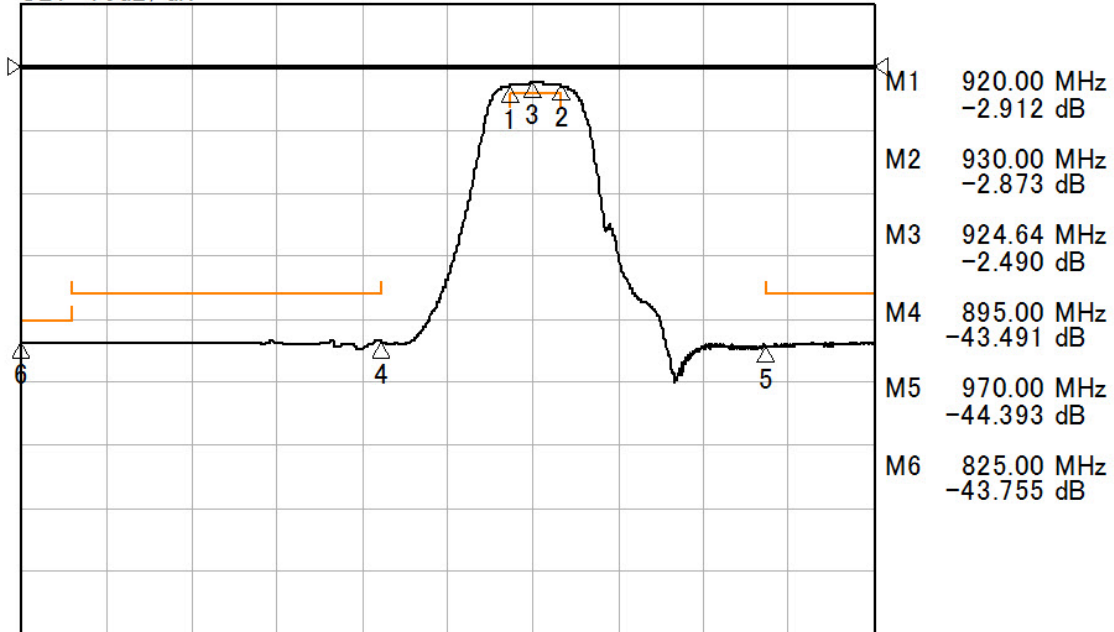
NOTES:

1. The design, manufacturing process, and specifications of this device are subject to change.
2. US or International patents may apply.

Transfer Function

Format: LogMag REF: 0dB

S21 10dB/div

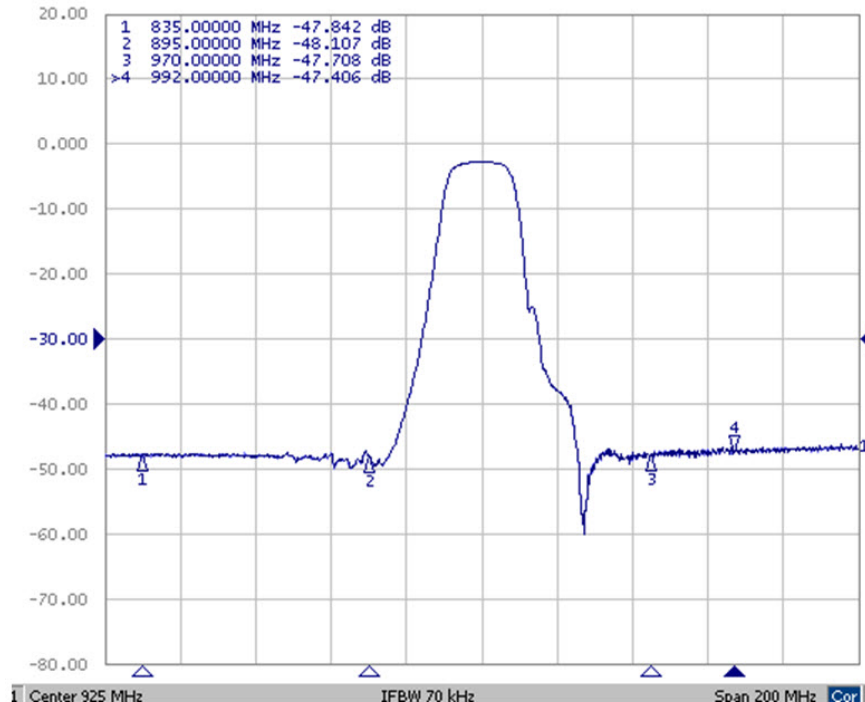


START 825.00 MHz

STOP 991.00 MHz 2016/10/13

Wideband

S21 Log Mag 10.00dB/ Ref -30.00dB [F2 D&M]



Center 925 MHz

IFBW 70 kHz

Span 200 MHz

SM3030-6 Case

6-Terminal Ceramic Surface-Mount Case 3.0 X 3.0 mm Nominal Footprint



PCB Footprint Top View

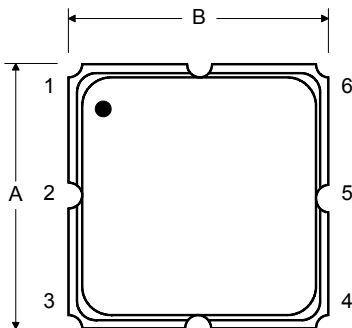
Case and PCB Footprint Dimensions

Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	-	3.00	-	-	0.118	-
B	-	3.00	-	-	0.118	-
C	-	-	1.40	-	-	0.054
D	-	-	1.00	-	-	0.039
E	-	2.80	-	-	0.110	-
F	-	1.60	-	-	0.063	-
G	-	0.85	-	-	0.033	-
H	-	1.50	-	-	0.059	-
I	-	0.60	-	-	0.024	-
J	-	1.30	-	-	0.051	-
K	-	3.20	-	-	0.126	-
L	-	1.70	-	-	0.067	-
M	-	1.05	-	-	0.041	-
N	-	0.81	-	-	0.032	-
O	-	0.38	-	-	0.015	-

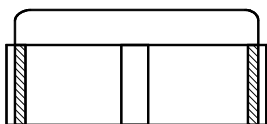
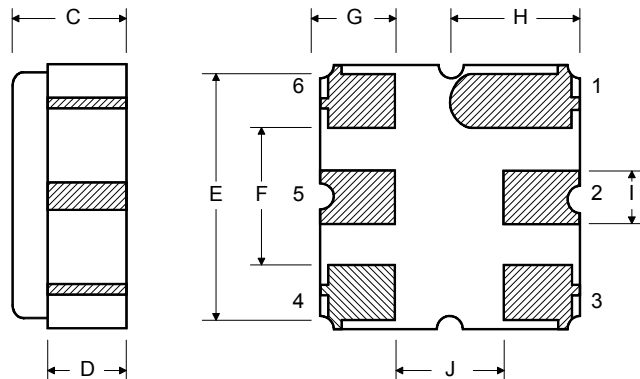
Case Materials

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

TOP VIEW

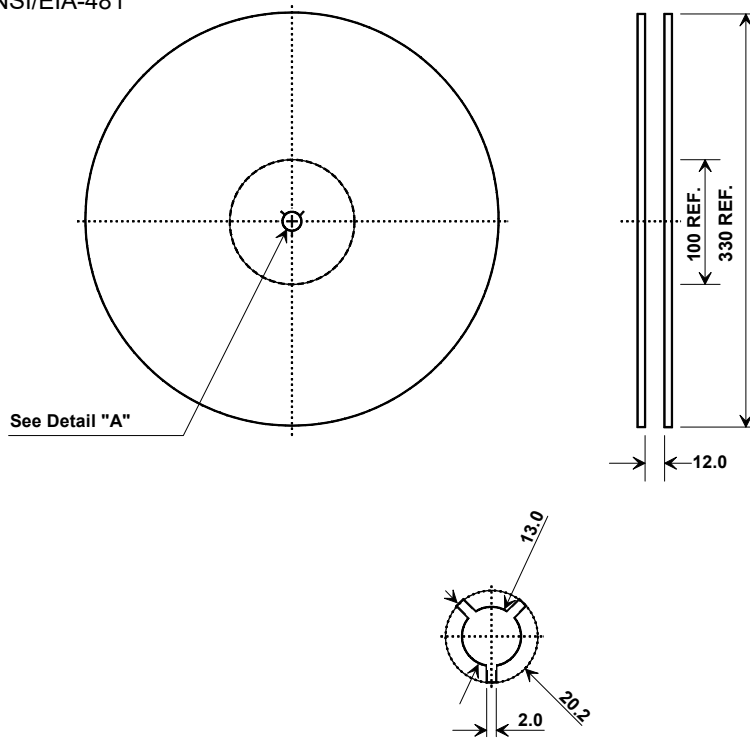


BOTTOM VIEW



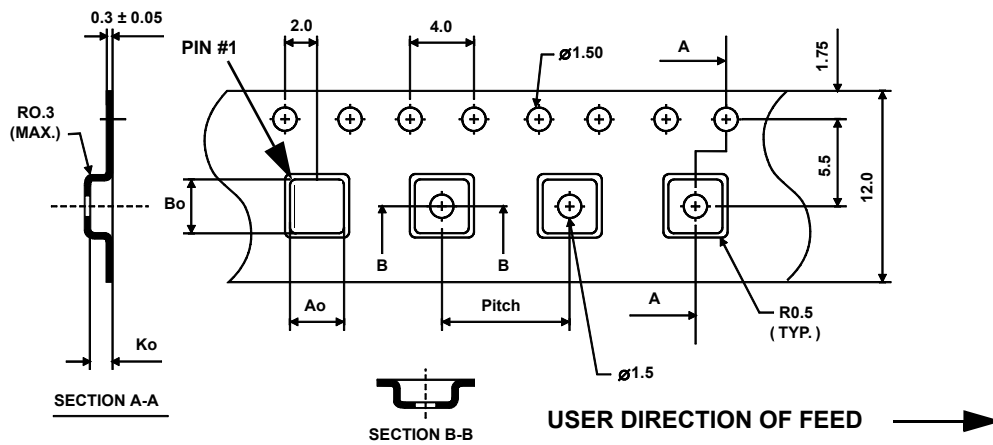
Tape and Reel Specifications

Tape and Reel Standard per ANSI/EIA-481



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	3.35 mm
Bo	3.35 mm
Ko	1.40 mm
Pitch	8.0 mm
W	12.0 mm



Recommended Reflow Profile

1. Preheating shall be fixed at 150~180°C for 60~90 seconds.
2. Ascending time to preheating temperature 150°C shall be 30 seconds min.
3. Heating shall be fixed at 220°C for 50~80 seconds and at 260°C +0/-5°C peak (10 seconds).
4. Time: 5 times maximum.

